

# AOC3864

## 20V Common-Drain Dual N-Channel AlphaMOS

### General Description

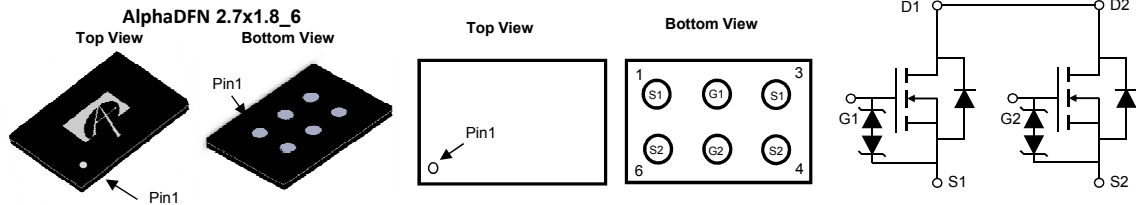
- Trench Power AlphaMOS (αMOS LV) technology
- Low  $R_{SS(ON)}$
- Fully protected AlphaDFN package
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS and Halogen-Free Compliant

### Applications

- Battery protection switch
- Mobile device battery charging and discharging

### Product Summary

$V_{SS}$	20V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$ )	< 5.7mΩ
$R_{SS(ON)}$ (at $V_{GS}=4.0V$ )	< 5.8mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.7V$ )	< 6mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$ )	< 7.5mΩ
$R_{SS(ON)}$ (at $V_{GS}=2.5V$ )	< 9mΩ
<b>Typical ESD protection</b>	<b>HBM Class 2</b>



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOC3864	AlphaDFN 2.7x1.8_6	Tape & Reel	5000

### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	$V_{SS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Source Current(DC) <sup>Note1</sup>	$I_S$	19	A
Source Current(Pulse) <sup>Note2</sup>	$I_{SM}$	80	
Power Dissipation <sup>Note1</sup>	$P_D$	2.4	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient $t \leq 10s$	$R_{\theta JA}$	43	$^\circ C/W$
Maximum Junction-to-Ambient Steady-State		52	$^\circ C/W$

**Note 1.**  $I_S$  rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

**Note 2.** PW < 10  $\mu s$  pulses, duty cycle 1% max.

Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>SSS</sub>	Source-Source Breakdown Voltage	I <sub>S</sub> =250μA, V <sub>GS</sub> =0V Test Circuit 6	20			V
I <sub>SSS</sub>	Zero Gate Voltage Source Current	V <sub>SS</sub> =20V, V <sub>GS</sub> =0V Test Circuit 1 T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate leakage current	V <sub>SS</sub> =0V, V <sub>GS</sub> =±8V Test Circuit 2			±10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>SS</sub> =V <sub>GS</sub> , I <sub>S</sub> =250μA Test Circuit 3	0.5	0.9	1.3	V
R <sub>SS(ON)</sub>	Static Source to Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>S</sub> =4A Test Circuit 4 T <sub>J</sub> =125°C	3.4	4.5	5.7	mΩ
			4.7	6.2	7.9	
		V <sub>GS</sub> =4.0V, I <sub>S</sub> =4A Test Circuit 4	3.5	4.6	5.8	mΩ
		V <sub>GS</sub> =3.7V, I <sub>S</sub> =4A Test Circuit 4	3.6	4.7	6.0	mΩ
		V <sub>GS</sub> =3.1V, I <sub>S</sub> =4A Test Circuit 4	3.7	5.2	7.5	mΩ
		V <sub>GS</sub> =2.5V, I <sub>S</sub> =4A Test Circuit 4	3.8	5.9	9.0	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>SS</sub> =5V, I <sub>S</sub> =4A Test Circuit 3		55		S
V <sub>FSS</sub>	Forward Source to Source Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V Test Circuit 5		0.60	1	V
<b>DYNAMIC PARAMETERS</b>						
R <sub>g</sub>	Gate resistance	f=1MHz		1		KΩ
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS1</sub> =4.5V, V <sub>SS</sub> =10V, I <sub>S</sub> =4A		27	38	nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS1</sub> =4.5V, V <sub>SS</sub> =10V, R <sub>L</sub> =2.5Ω, R <sub>GEN</sub> =3Ω Test Circuit8		1.2		μs
t <sub>r</sub>	Turn-On Rise Time			2.2		μs
t <sub>D(off)</sub>	Turn-Off DelayTime			5.5		μs
t <sub>f</sub>	Turn-Off Fall Time			6.5		μs

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

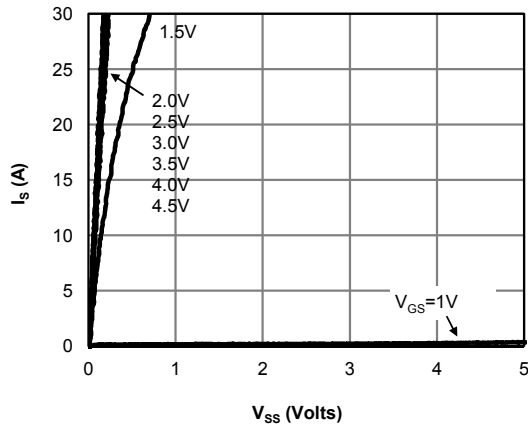


Figure 1: On-Region Characteristics

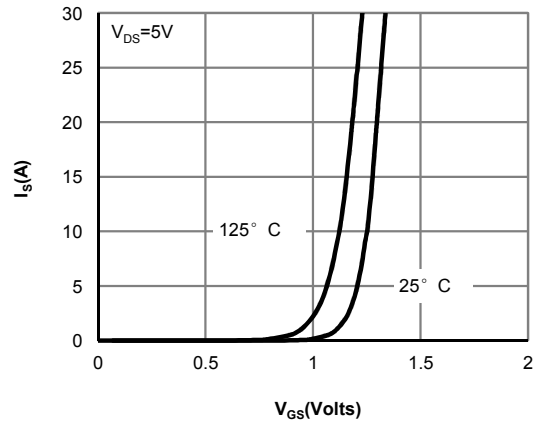


Figure 2: Transfer Characteristics

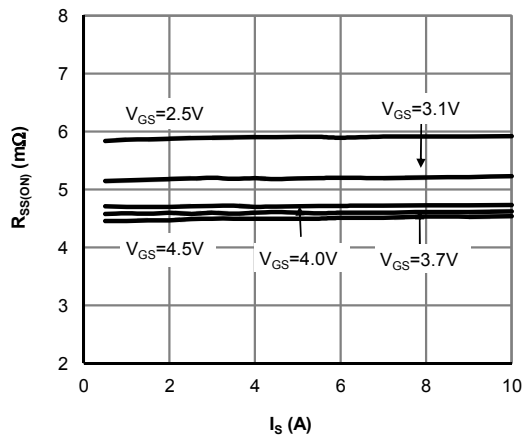


Figure 3: On-Resistance vs. Source Current and Gate Voltage

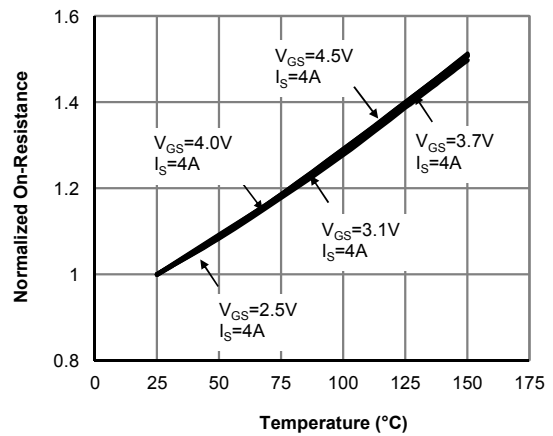


Figure 4: On-Resistance vs. Junction Temperature

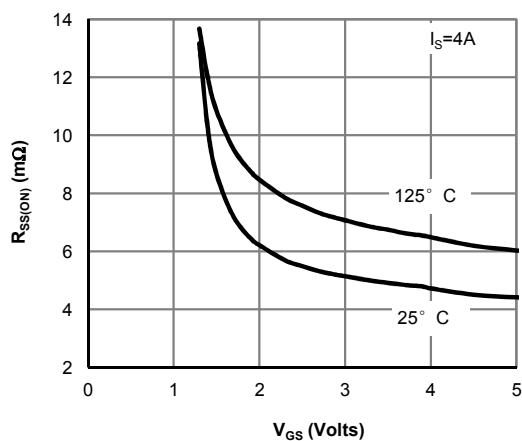


Figure 5: On-Resistance vs. Gate-Source Voltage

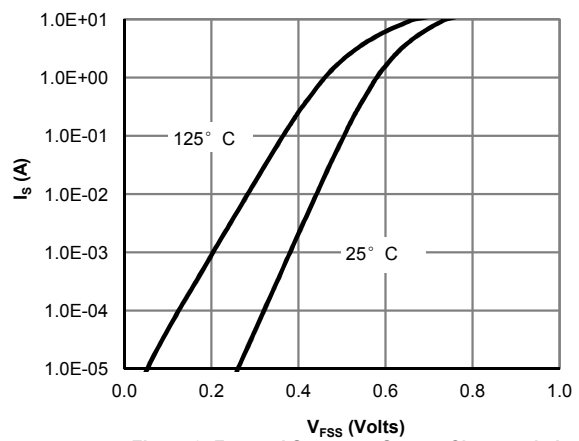


Figure 6: Forward Source to Source Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

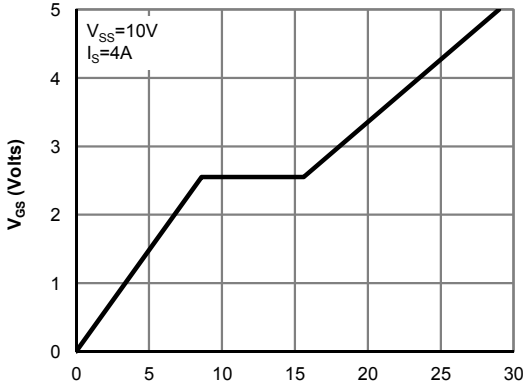


Figure 7: Gate-Charge Characteristics

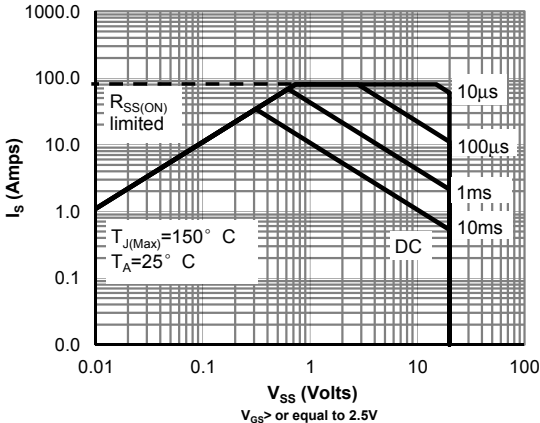


Figure 9: Maximum Forward Biased Safe Operating Area (Note1)

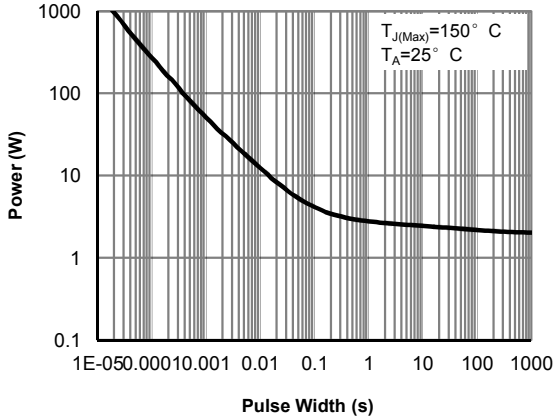


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note1)

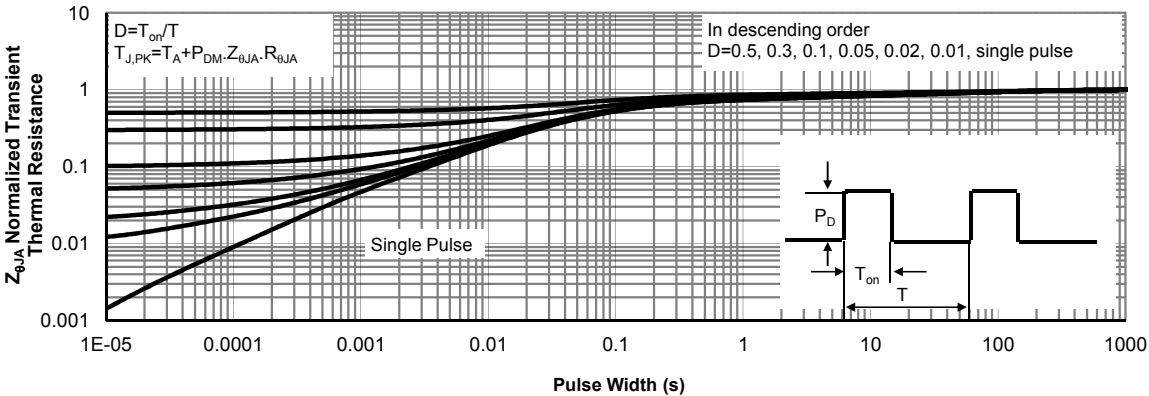
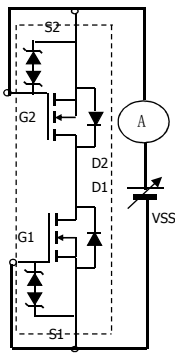


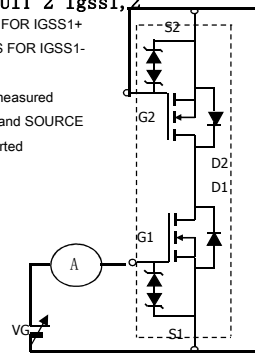
Figure 11: Normalized Maximum Transient Thermal Impedance (Note1)

**TEST CIRCUIT 1  $I_{SSS}$**   
 POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-



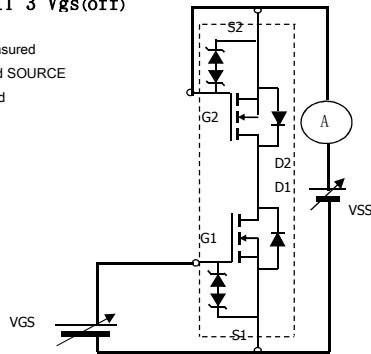
**TEST CIRCUIT 2  $I_{GSS1,2}$**   
 POSITIVE VGS FOR IGSS1+  
 NEGATIVE VGS FOR IGSS1-

When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted



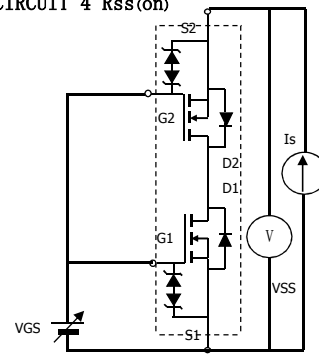
**TEST CIRCUIT 3  $V_{GS(off)}$**

When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted



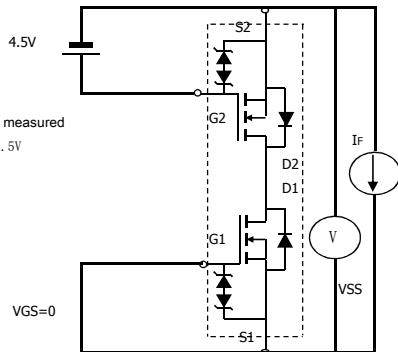
**TEST CIRCUIT 4  $R_{SS(on)}$**

VSS/Is



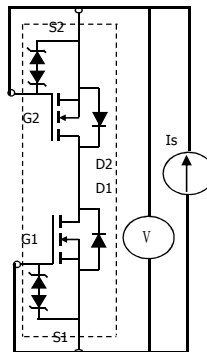
**TEST CIRCUIT 5  $V_{F(SS)1,2}$**

When FET1 measured  
 FET2  $V_{GS}=4.5V$



**TEST CIRCUIT 6  $BV_{DSS}$**

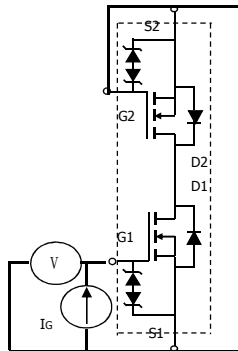
POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-



**TEST CIRCUIT 7  $BV_{GS01,2}$**

POSITIVE VSS FOR ISSS+  
 NEGATIVE VSS FOR ISSS-

When FET1 is measured  
 between GATE and SOURCE  
 of FET2 are shorted



**TEST CIRCUIT 8**  
 Switching time

